

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	492	(semi adj cured semicured semi-cured)same (cut dice separated)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 08:14
L2	449	1 and cured	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 11:14
L3	459	1 and (second again cured)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 08:16
L4	0	1 and (second with again with cured)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 08:15
L5	11	1 and (second same again same cured)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 08:15
L6	84	PREPREG AND (B ADJ STAGE SAME (CUT DICE DICING DICED SAW)) AND (SEMICONDUCTOR CHIP DIE)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 11:19
L7	30	PREPREG AND (B ADJ STAGE WITH (CUT DICE DICING DICED SAW)) AND (SEMICONDUCTOR CHIP DIE)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 11:19
L8	128	(B ADJ STAGE WITH (CUT DICE DICING DICED SAW)) AND (SEMICONDUCTOR CHIP DIE)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 12:35

## EAST Search History

L10	0	b adj stageable with sheet and (semiconductor chip die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 14:59
L11	473	b adj stage with sheet and (semiconductor chip die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 16:28
L12	278	bum adj through	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 16:29
L13	1	bum adj through and b adj stage	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 16:30
L14	1	bum adj through and b adj stageable	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 16:30
L15	3	burn adj through and b adj stageable	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 16:31
L16	17	burn adj through and b adj stage	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 16:32
L17	5	push adj through and b adj stage	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/30 16:32

## EAST Search History

S1	2	("20040198023").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/30 14:58
S2	4	((("6064114") or ("5977641"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/29 15:08
S3	248	(heal prevent reduce fix repair) with (crack or delamination) same (protective encapsulent encapsulate encapsulating protecting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:42
S4	2102	partial adj cure	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:42
S5	16481	S3 adn S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:41
S6	1	S3 and S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:41
S7	3751	partially adj cure	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:42
S8	0	S3 and S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:42

## EAST Search History

S9	1523	(crack or delamination) same (protective encapsulant encapsulate encapsulating protecting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:42
S10	3	S7 and S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:48
S11	2474	(crack delamination) same (dicing cutting scribing separating) and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 12:49
S12	4678	(crack delamination) same (dice dicing cutting scribing scribe cut separate separating) and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 14:18
S13	44848	(crack delamination) same (dice dicing cutting scribing scribe cut separate separating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 14:18
S14	89998	(crack delamination defect) same (dice dicing cutting scribing scribe cut separate separating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:36
S15	4039166	resin epoxy encapsulant protective coating	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 14:21
S16	13991	S14 same S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 14:21

## EAST Search History

S17	9194905	(repair mend fix bushel doctor furbish up, restore touch adj on better improve amend ameliorate meliorate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 14:26
S18	9202203	(repair mend fix bushel doctor furbish up, restore touch adj on better improve amend ameliorate meliorate heal)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 14:26
S19	5235	S16 same S18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 14:27
S20	351	S19 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 14:27
S21	105080	(cur\$3 or harden\$3) with polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:27
S22	30	S20 and S21	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:09
S23	1	("6885108").URPN.	USPAT	OR	ON	2006/08/29 15:19

## EAST Search History

S24	54	("20020066966"   "20020098623"   "20020171177"   "20020182782"   "20030003180"   "20030003380"   "20030003405"   "20030043360"   "20030068584"   "20030072926"   "20030077418"   "20030089999"   "20030092220"   "20030093173"   "20030102566"   "20030129787"   "20030151167"   "20030201531"   "20030203158"   "20030207213"   "3978578"   "4033027"   "5157001"   "5462636"   "5682065"   "5742094"   "5933713"   "5956605"   "5977641"   "6210993"   "6251488"   "6259962"   "6268584"   "6326698"   "6337122"   "6353267"   "6391251"   "6399178"   "6432752"   "6482576"   "6489007"   "6514798"   "6524346"   "6544821"   "6544902"   "6549821"   "6562278"   "6562647"   "6585927"   "6593171"   "6620731"   "6635333"   "6849524"   "6885108").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/29 15:26
S25	23968	(recur\$3 re-cur\$3 re adj cur\$3 or re adj harden\$3 re-harden\$3 reharden\$3 harden\$3) with polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:34
S26	4854	b-stage b-stagable	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:29
S27	116	S25 and S26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:29
S28	841	(recur\$3 re-cur\$3 re adj cur\$3 or re adj harden\$3 re-harden\$3 reharden\$3 ) with polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:40

## EAST Search History

S29	7	S26 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:34
S30	16	S14 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:36
S31	0	S28 and (dice dicing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:40
S32	44	cured after diced	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2006/08/29 15:54
S33	2	semi adj cured diced	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2006/08/29 15:55
S34	0	semi adj cure diced	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2006/08/29 15:55
S35	3504	semi adj cured	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2006/08/29 15:55
S36	0	semi adj cured (cut dice separated)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	WITH	ON	2006/08/29 15:55